

AMENDMENTS TO THE CLAIMS

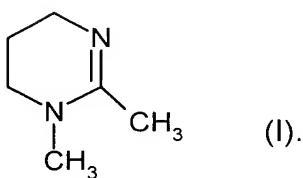
This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

Claims 1-12. (Cancelled)

Claim 13. (Currently Amended): A solventless reactive system, which is curable at room temperature and which comprises

- A) a polyisocyanate component comprising at least one organic polyisocyanate having a molecular weight, excluding the weight of the blocking agent, of 168 to 25,000 and in which at least 95 mole % of the NCO groups are reversibly blocked with at least one hydrocarbon resin containing phenolic OH groups and having ~~a hydroxyl group~~ an OH content (calculated as OH, molecular weight 17) of 0.1% to 10.0%, based on the weight of the hydrocarbon resin, wherein the hydrocarbon resin is prepared by copolymerizing phenol in the presence of strong acids or catalysts with one or more unsaturated hydrocarbons selected from the group consisting of butene, butadiene, pentene, piperylene, isoprene, cyclopentadiene, styrene, α -methylstyrene, vinyltoluene, dicyclopentadiene, methyldicyclopentadiene, indene and methylindene,
- B) at least one organic amine having at least 2 primary amino groups,
- C) an oxirane compound containing more than one epoxy group per molecule and
- D) a catalyst comprising 2,3-dimethyl-3,4,5,6-tetrahydropyrimidine of formula (I):



Claim 14. (Previously Presented): The solventless reactive system of Claim 13 wherein said organic polyisocyanate comprises an isocyanate group-containing prepolymer prepared by reacting (i) an aromatic polyisocyanate having a molecular weight of 174 to 300 and (ii) an ether and/or ester group-containing organic polyhydroxyl compound having a molecular weight of 1000 to 8000, in which the isocyanate groups are reversibly blocked by reaction with at least one phenolic OH group-containing hydrocarbon resin having a hydroxyl group content (calculated as OH, molecular weight 17) of 0.1% to 10.0%.

Claim 15. (Previously Presented): The solventless reactive system of Claim 13 wherein the isocyanate groups of component A) are reversibly blocked by reaction with a hydrocarbon resin which contains phenolic OH groups, is liquid at room temperature and has a hydroxyl group content of 1.5% to 4.0%.

Claim 16. (Previously Presented): The solventless reactive system of Claim 14 wherein the isocyanate groups of component A) are reversibly blocked by reaction with a hydrocarbon resin which contains phenolic OH groups, is liquid at room temperature and has a hydroxyl group content of 1.5% to 4.0%.

Claim 17. (Previously Presented): The solventless reactive system of Claim 13 wherein component B) comprises at least one diamine containing at least one cycloaliphatic ring and having a maximum molecular weight of 500.

Claim 18. (Previously Presented): The solventless reactive system of Claim 14 wherein component B) comprises at least one diamine containing at least one cycloaliphatic ring and having a maximum molecular weight of 500.

Claim 19. (Previously Presented): The solventless reactive system of Claim 15 wherein component B) comprises at least one diamine containing at least one cycloaliphatic ring and having a maximum molecular weight of 500.

Claim 20. (Previously Presented): The solventless reactive system of Claim 16 wherein component B) comprises at least one diamine containing at least one cycloaliphatic ring and having a maximum molecular weight of 500.

Claim 21. (Previously Presented): The solventless reactive system of Claim 13 wherein component C) comprises a liquid epoxy resin that is the reaction product of epichlorohydrin and 2,2-diphenylolpropane (bisphenol A) or diphenylolmethane (bisphenol F).

Claim 22. (Previously Presented): The solventless reactive system of Claim 14 wherein component C) comprises a liquid epoxy resin that is the reaction product of epichlorohydrin and 2,2-diphenylolpropane (bisphenol A) or diphenylolmethane (bisphenol F).

Claim 23. (Previously Presented): The solventless reactive system of Claim 15 wherein component C) comprises a liquid epoxy resin that is the reaction product of epichlorohydrin and 2,2-diphenylolpropane (bisphenol A) or diphenylolmethane (bisphenol F).

Claim 24. (Previously Presented): The solventless reactive system of Claim 16 wherein component C) comprises a liquid epoxy resin that is the reaction product of epichlorohydrin and 2,2-diphenylolpropane (bisphenol A) or diphenylolmethane (bisphenol F).

Claim 25. (Previously Presented): The solventless reactive system of Claim 17 wherein component C) comprises a liquid epoxy resin that is the reaction product of epichlorohydrin and 2,2-diphenylolpropane (bisphenol A) or diphenylolmethane (bisphenol F).

Claim 26. (Previously Presented): The solventless reactive system of Claim 18 wherein component C) comprises a liquid epoxy resin that is the reaction product of epichlorohydrin and 2,2-diphenylpropane (bisphenol A) or diphenylmethane (bisphenol F).

Claim 27. (Previously Presented): The solventless reactive system of Claim 19 wherein component C) comprises a liquid epoxy resin that is the reaction product of epichlorohydrin and 2,2-diphenylpropane (bisphenol A) or diphenylmethane (bisphenol F).

Claim 28. (Previously Presented): The solventless reactive system of Claim 20 wherein component C) comprises a liquid epoxy resin that is the reaction product of epichlorohydrin and 2,2-diphenylpropane (bisphenol A) or diphenylmethane (bisphenol F).

Claim 29. (Previously Presented): The solventless reactive system of Claim 13 wherein component D) is used in an amount of 0.5 to 3 wt.%, based on the weight of components A) and C).

Claim 30. (Previously Presented): The solventless reactive system of Claim 28 wherein component D) is used in an amount of 0.5 to 3 wt.%, based on the weight of components A) and C).

Claim 31. (Previously Presented): An adhesive, sealant, casting compound, molded article or coating prepared from the solventless reactive system of Claim 13.

Claim 32. (Previously Presented): A coating prepared from the solventless reactive system of Claim 13.